

Abstract**Insert carrier and method for the simultaneous double-side material-removing processing of semiconductor wafers**

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The invention relates to an insert carrier, suitable for receiving one or a plurality of semiconductor wafers for the double-side processing thereof between
10 two working disks of a lapping, grinding or polishing apparatus, comprising a core composed of a first material having a first and a second surface, wherein the first and the second surface each bear a coating composed of a second material, said coating completely
15 or partly covering the first and second surfaces, and also at least one opening for receiving a semiconductor wafer, wherein that surface of the coating which is remote from the core has a structuring consisting of elevations and depressions, characterized in that the
20 correlation length of the elevations and depressions of the structuring is in the range of 0.5 mm to 25 mm and the aspect ratio of the structuring is in the range of 0.0004 to 0.4.

25 The invention also relates to a method for the simultaneous double-side material-removing processing of semiconductor wafers in which the insert carrier is used.

30 Fig. 5